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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Byoung Hwa LEE	08/28/2008
Sung Kwon WI	08/28/2008
Hae Suk CHUNG	08/29/2008
Dong Seok PARK	08/28/2008
Sang Soo PARK	08/28/2008
Min Cheol PARK	08/28/2008

RECEIVING PARTY DATA

Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.	
Street Address:	314, Maetan 3-dong, Yeongtong-gu, Suwon,	
City:	Gyunggi-do	
State/Country:	REPUBLIC OF KOREA	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12245865

CORRESPONDENCE DATA

Fax Number: (202)756-8087

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 202-756-8000 Email: Kadkins@mwe.com

Correspondent Name: MCDERMOTT WILL & EMERY LLP

Address Line 1: 600 13TH STREET, N.W.

Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20005-3096

ATTORNEY DOCKET NUMBER:	069576-0417
NAME OF SUBMITTER:	Stephen A. Becker

PATENT REEL: 021635 FRAME: 0799

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Total Attachments: 3

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PATENT REEL: 021635 FRAME: 0800

RECORDATION FORM COVER SHEET			
Docket No.: 069576-0417 PATENTS			
To the Director of the U. S. Patent and Trademark Office: Please 1	ecord the attached documents or the new address(es) below.		
1. Name of Conveying Party(ies)	2. Name and address of receiving party(ies)		
Byoung Hwa LEE, Sung Kwon WI, Hae Suk CHUNG, Dong	Name: SAMSUNG ELECTRO-MECHANICS CO.,		
Seok PARK, Sang Soo PARK, Min Cheol PARK	LTD.		
	Internal Address:		
Additional name(s) of conveying party(ies) attached? Yes No			
3. Nature of Conveyance/Execution Date(s)	Address: 314, Maetan 3-dong, Yeongtong-gu, Suwon,		
	Gyunggi-do, REPUBLIC OF KOREA		
Execution Date(s): August 28, 2008; August 28, 2008; August			
29, 2008; August 28, 2008; August 28,			
2008 and August 28, 2008 respectively			
Security Agreement Change of Name			
☐ Joint Research Agreement			
Government Interest Assignment			
☐ Executive Order 9424, Confirmatory License			
Other	Additional name(s) & address(es) attached? Yes No		
4. Application or patent number(s):	This document is being filed together with a new application.		
A. Patent Application No(s).	B. Patent No(s).		
Additional numbers attac			
5. Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:		
Name: MCDERMOTT WILL & EMERY LLP	7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00		
Internal Address:	Authorized to be charged by credit card		
monar radios.	Authorized to be charged to deposit account		
Street Address: 600 13th Street, N.W.	☐ Enclosed		
	None required (government interest not affecting title)		
City: Washington State: D. C. Zip: 20005-3096			
Phone Number: 202.756.8000	8. Payment Information:		
Fax Number: 202.756.8087			
Email Address:	a. Credit Card Last 4 Numbers		
	Expiration Date		
	b. Deposit Account Number 500417		
	Authorized User Name		
9. Signature.			
Stephen A. Becker 26,527	October 6, 2008		
Name and Registration No. of Person Signing	Signature Date		
	ng cover sheet, attachments and documents: 3		

PATENT REEL: 021635 FRAME: 0801

(SAB)
Docket No.:
ASSIGNMENT
In consideration of the premises and other good and valuable consideration in hand paid, the receipt and
sufficiency of which is hereby acknowledged, the undersigned,
(1) LEE, Byoung Hwa (5) PARK, Sang Soo
(2) WI, Sung Kwon (6) PARK, Min Cheol (3) CHUNG, Hae Suk (7)
(3) CHUNG, Hae Suk (7)
(4) PARK, Dong Seok (8)
who have made a certain new and useful invention, hereby sell, assign and transfer unto
SAMSUNG ELECTRO-MECHANICS CO., LTD.
314, Maetan 3-dong, Yeongtong-gu, Suwon, Gyunggi-do, Republic of Korea
its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of
America as defined in 35 U.S.C. 100 in the invention entitled
MULTILAYER CHIP CAPACITOR
(a) for which an application for United States Letters Patent was filed on,
and identified by United States Serial No; or
and identified by Offited States Seriai No, or
(h) for which are application for I wited States I offers Detent was everyted on
(b) for which an application for United States Letters Patent was executed on
and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any
and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues,
substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International
Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors,
assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act
on behalf of said ASSIGNEE;
AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making
application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS

DATE SIGNED

1) _____

Name: LEE, Byoung Hwa

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4) Park

2008.08.28

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Name. FARK, Sang 300

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6) Oh Min

Name: PARK, Min Cheol

RECORDED: 10/06/2008